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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/901,526	07/09/2001	Matthias Forster	INF-1078	7099

7590

05/06/2003

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EXAMINER		
MULPURI, SAVITRI	•	

PAPER NUMBER

ART UNIT

DATE MAILED: 05/06/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

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Office Action Summary

Application No. 09/901,526

Applicant(s)

Forester et al

Examiner

Savitri Mulpuri

Art Unit 2812

The MAILING DATE of this co	mmunication appears on th	he cover sheet with the corres				
Period for Reply						
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.						
 Extensions of time may be available under the provis mailing date of this communication. If the period for reply specified above is less than thin. If NO period for reply is specified above, the maximuter a reply within the set or extended period for any reply received by the Office later than three more aerned patent term adjustment. See 37 CFR 1.704. 	irty (30) days, a reply within the stat am statutory period will apply and will reply will, by statute, cause the appl nths after the mailing date of this co	utory minimum of thirty (30) days will be Il expire SIX (6) MONTHS from the mailin lication to become ABANDONED (35 U.S	considered timely. g date of this communication. .C. § 133).			
Status						
1) 💢 Responsive to communication	s) filed on <i>Feb 12, 2003</i>		<u> </u>			
2a) X This action is FINAL .	2b)□ This action i	s non-final.				
	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11; 453 O.G. 213.					
Disposition of Claims						
4) 💢 Claim(s) <u>11-23</u>		is/are	pending in the application.			
4a) Of the above, claim(s)		is/are	e withdrawn from consideration.			
5) Claim(s)			s/are allowed.			
6) 💢 Claim(s) <u>11-23</u>			s/are rejected.			
7) Claim(s)			s/are objected to.			
8) 🗌 Claims		are subject to restric	tion and/or election requirement.			
Application Papers						
9) \square The specification is objected to	by the Examiner.					
10) The drawing(s) filed on	is/are a) [accepted or b) objecte	d to by the Examiner.			
Applicant may not request that	any objection to the drawi	ng(s) be held in abeyance. See	37 CFR 1.85(a).			
11) The proposed drawing correct	ion filed on	is: a) 🗌 approved	b) \square disapproved by the Examiner.			
If approved, corrected drawings	are required in reply to the	is Office action.				
12) The oath or declaration is obje	cted to by the Examiner.					
Priority under 35 U.S.C. §§ 119 and 1	20					
13) Acknowledgement is made of	a claim for foreign priorit	y under 35 U.S.C. § 119(a)-	(d) or (f).			
a)□ All b)□ Some* c)□ Ne	one of:					
 Certified copies of the pr 	iority documents have be	en received.				
2. Certified copies of the pr	iority documents have be	en received in Application N	0			
• •	he International Bureau (f	PCT Rule 17.2(a)).	this National Stage			
*See the attached detailed Office		·				
14) Acknowledgement is made of			e).			
a) U The translation of the foreign) and/or 4.24			
15) Acknowledgement is made of	a claim for domestic prio	rity under 35 U.S.C. 33 120	and/or 121.			
Attachment(s) 1) Notice of References Cited (PTO-892)	ړ، ⊏	Interview Summan, IDTO 4121 De A	lofel			
Notice of Praftsperson's Patent Drawing Review	_	Interview Summary (PTO-413) Paper N Notice of Informal Patent Application (I				
Information Disclosure Statement(s) (PTO-1449)	· ·	Other:				
						

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DETAILED ACTION

This action is in response to the applicant's amendment and declaration under rule 131, filed on 2/1/203.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

(e) the invention was described in-

- (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effect under this subsection of a national application published under section 122(b) only if the international application designating the United States was published under Article 21(2)(a) of such treaty in the English language; or
- (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that a patent shall not be deemed filed in the United States for the purposes of this subsection based on the filing of an international application filed under the treaty defined in section 351(a).

Claims 12- 16, 18- 19, 21-23 are rejected under 35 U.S.C. 103(a) as being unpatentable over Thakur et al (US 6,187,628).

Thakur et al discloses a method of growing silicon layer with micro roughness or hemispherical growth by the following process: Providing a substrate "12" in a chemical vapor deposition process chamber; growing polysilicon layer "16" over the substrate; growing a thin oxide layer "18"; generating a process gas containing semiconductor material to grow a rough polysilicon silicon layer "20" in in-situ chemical vapor depositition. Thakur teaches without annealing the rough silicon layer "20", growing dielectric layer "20". Thakur et al grows silicon layer in single growth

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step exactly similar to what is claimed in instant process Thakur et al discloses providing silane gas at growth temperature 500-700 C and pressure in the range of 70 m Torr to 50 Torr, which is with in claimed pressure (100 m torr 600 mTorr) to produce rough polysilicon with the thickness in the range of 300 angstroms to 100 angstroms (see fig. 1 and col. 3, lines 23-47). Thakur et al further discloses precleaning the substrate in HF prior to growth to inherently provide oxide free surface because HF etches natural oxide deposited on silicon substrate surface (see col. 2, lines 50-54). Thakur et al discloses the whole process is applied to form either trench or stacked capacitor for DRAMs (see col. 1, lines 24-27). Since similar operating conditions, as claimed growth conditions, are set to grow rough polysilicon in Thakur et al, it is inherent that growth period in Thakur et al is similar to instant claimed growth time period.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 17, 20 are rejected under 35 U.S.C. 103(a) as being unpatentable over Thakur et al in combination with Lin (US 6,127,221) or Yew (US 5,753,359) discloses a method of making rough polysilicon in a single growth step with out annealing step at similar growth conditions as growth conditions recited in instant claimed conditions. Tahkur et al does not teach hydrogen: silane ratio or nitrogen: silane ratio to grow rough polysilicon.

Lin et al teaches silane concentration 10 E--3/m³ in nitrogen ambient, which imply that nitrogen content is more compared with silane (see fig.5 spacious hemispherical grains and col. 5, lines 1-18). Yew discloses ratio of hydrogen to silane is 98 percent (see abstract and col. 7, lines 40-56). It would have been obvious to one of ordinary

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skill in the art to use heavy dilution of silane with nitrogen or hydrogen for hemispherical growth because Lin or Yew teaches the suitability of nitrogen to silane or hydrogen diluted silane is suitable for hemispherical growth. Since the dilution is more roughness is more, selecting the ratio of hydrogen or nitrogen to silane would have been well within the one of ordinary skill in the art depending on the required degree of roughness of the polysilicon and required thickness of capacitance fro DRAMs.

Applicant's arguments with respect to claims 12-23 have been considered but are moot in view of the new ground(s) of rejection.

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action.

Accordingly, **THIS ACTION IS MADE FINAL.** See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to S. Mulpuri whose telephone number is 703-305-5184. The fax phone number for the organization where this application or proceeding is assigned is 703-308-7722.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

SAVITRI MULPURI PRIMARY EXAMINER

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